

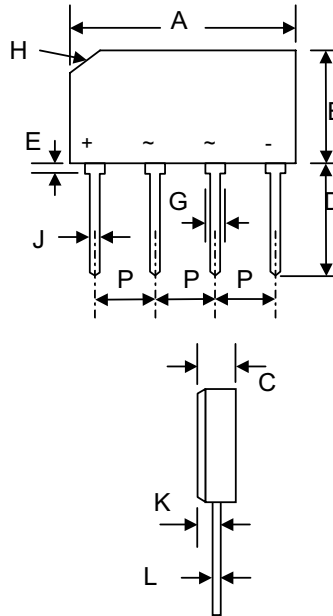
Data Sheet 1331, Rev.B

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- UL Recognized File # E223064

Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 2.0 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



Dim	GBL			
	Min	Max	Min	Max
A	20.7	20.9	0.815	0.823
B	10.4	10.7	0.409	0.421
C	3.2	3.6	0.126	0.142
D	17.5	18.5	0.689	0.728
E	1.50	2.2	0.059	0.087
G	2.12	2.4	0.083	0.094
H	3.17 x 45°		0.125 x 45°	
J	0.90	1.20	0.035	0.047
K	1.15	1.55	0.045	0.061
L	0.45	0.65	0.018	0.026
P	4.8	5.3	0.189	0.209
	In mm		In inch	

Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	GBL 005	GBL 01	GBL 02	GBL 04	GBL 06	GBL 08	GBL 10	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_A = 50^{\circ}\text{C}$	I_O	4.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	150							A
Forward Voltage (per bridge) @ $I_F = 4.0\text{A}$	V_{FM}	1.0							V
Peak Reverse Current @ $T_A = 25^{\circ}\text{C}$ At Rated DC Blocking Voltage @ $T_C = 150^{\circ}\text{C}$	I_R	10 1.0							μA mA
Typical Thermal Resistance (per leg) (Note 1)	$R_{\theta JA}$	22							$^{\circ}\text{C/W}$
Typical Thermal Resistance (per leg) (Note 2)	$R_{\theta JC}$	3.5							$^{\circ}\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150							$^{\circ}\text{C}$

Note: 1. Thermal resistance junction to ambient, mounted on 7.5 x 7.5 x 0.3cm thick AL plate.
2. Thermal resistance junction to case, mounted on PCB at 9.5mm lead length.

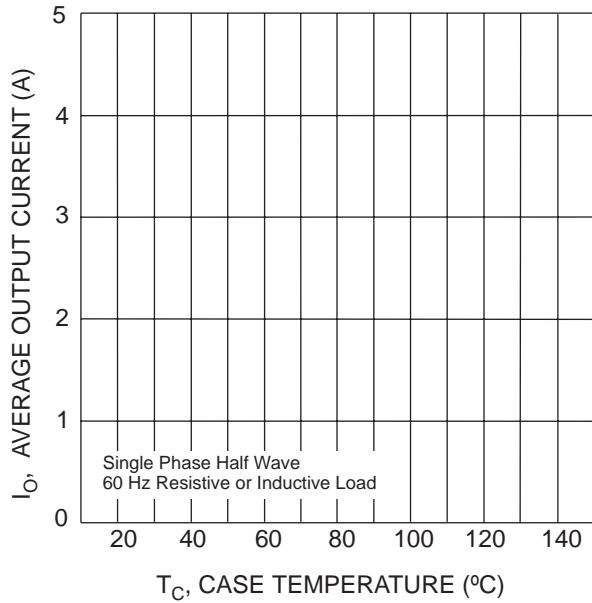


Fig. 1 Forward Current Derating Curve

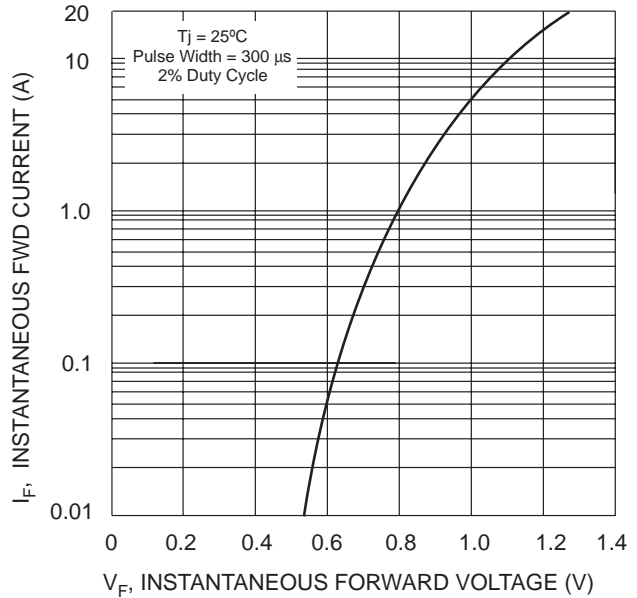


Fig. 2 Typical Forward Characteristics, per element

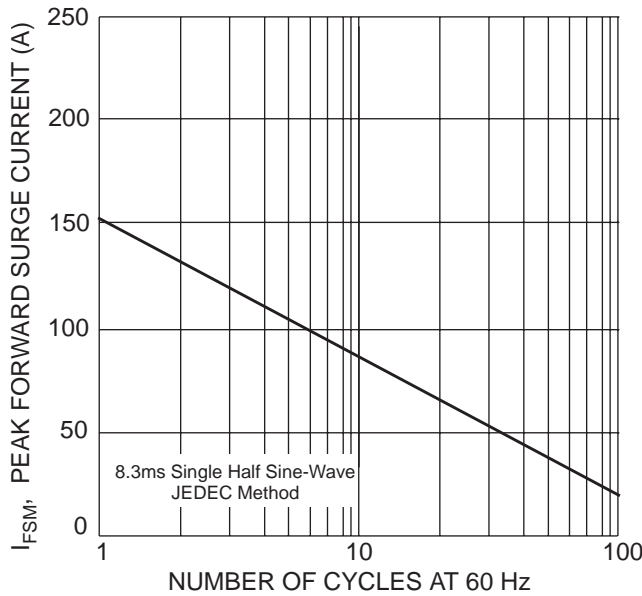


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

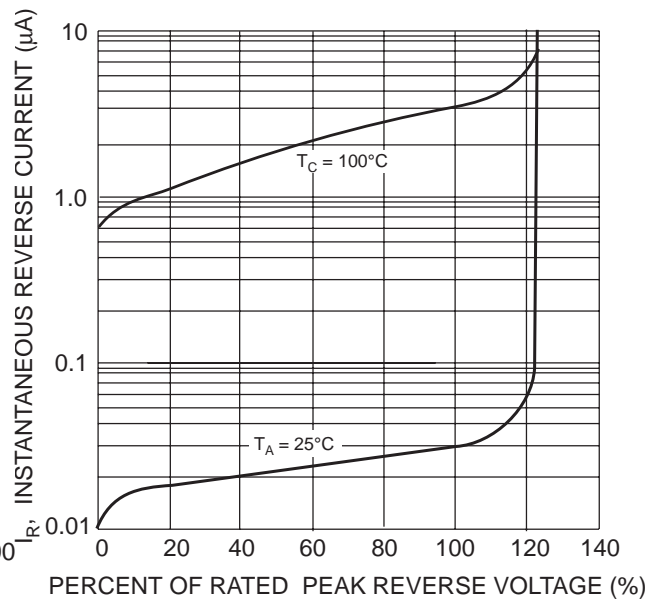


Fig. 4 Typical Reverse Characteristics, per element

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